



SPECIFICATIONS:

MATERIALS:

CLADDING:

SOLDER MASK:

SILK SCREEN:

SURFACE FINISH:

INTENTIONAL SHORTS:

TEST REQUIREMENTS:

HOLE TOLERANCE

UNLESS SPECIFIED
PLATED: +/- .3 MILS
NON PLATED: +/- .3 MIL

FINISHED HOLES IN MILS			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY TOLERANCE/NOTES
A	10.0	PLATED	529 SEE NOTE 15
O	50.0	NON-PLATED	1

2 LAYER STACKUP

- PRIMARY SILKSCREEN
- PRIMARY SOLDER MASK
- ROGERS 4300 10 MIL
- PRIMARY SIDE (LAYER 1)
- SECONDARY SIDE (LAYER 2)

NOMINAL
FINISHED
BOARD
THICKNESS
14-17 MILS

REV		DESCRIPTION		DATE		APPROVED	
A		INITIAL RELEASE		02/2017		H.G.	

1 2 3 4 5 6 7 8

REQUIREMENTS:

1. REFER TO IPC-4101 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
2. ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TS7000115, (LATEST REVISION.)
3. MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
4. HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.003 INCHES FROM THEIR TRUE POSITION.
5. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.
6. HOLE DIAMETERS APPLY AFTER PLATING.
7. FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
8. MINIMUM DESIGN LINE WIDTH IS .008 INCH.
9. MINIMUM PAD SPACING IS .006 INCH.
10. NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.
11. IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN THE MINIMUM DESIGN LINE WIDTH, THE DESIGNER SHALL PROVIDE TEAR DROP PADS TO MAINTAIN ANNUAL RINGS (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)
12. THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER.
13. A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, TEAR DROP PADS, AND OTHER AREAS SHALL BE MAINTAINED. B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.
14. MFR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT UNLESS OTHERWISE INDICATED. D. MFR LOGO E. SUCCESSFUL ELECTRICAL TEST.
15. REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED. GOLD SEC ARTWORK LAYERS WHEN PROVIDED IN GERBER OR ODB++ DATA, INDICATED HOLES ARE TO BE NON-CONDUCTIVE EPOXY FILLED AND GROUND FLUSH TO 3 MILS BELOW SURFACE PRIOR TO PLATING OVER.
16. CRITICAL LINE WIDTH 0.016 +/- 0.001" PRIMARY SIDE. ADJUST PROCESS TO ACHIEVE WIDTH.

PRIMARY SIDE

PRIMARY SIDE	REPAIRS PER IPC-711/21 (LATEST REV.) ARE ALLOWED.	
	GOLD-SEC AIRWORK LAYERS WHEN PROVIDED IN GERBER OR GER++ DATA.	
	FLUOR-TO MILLS BELOW SURFACE PRIOR TO PLATING OVER.	
	CRITICAL LINE WIDTH. 0.018 +/- 0.001- PRIMARY SIDE. ADJUST PROCESS TO ACHIEVE WIDTH.	
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